

**AMENDMENTS TO THE CLAIMS:**

Please cancel claim 5, without prejudice or disclaimer of its subject matter, and amend claims 1, 4, and 6-13, as indicated below. This listing of claims will replace all prior versions and listings of claims in the application:

**LISTING OF CLAIMS:**

1. (Currently Amended) A method of manufacturing a semiconductor device, comprising:

sectioning semiconductor elements from a semiconductor wafer to provide at least first and second semiconductor elements, which has an element region formed on its front surface, while keeping the sectioned first and second semiconductor elements in a state held by a holding member;

picking up the sectioned first and second semiconductor elements from the holding member by holding them with an absorption collet in order of their sectioning;

cutting an element adhesive film held by a porous absorption member according to the shape of one of the semiconductor elements to form a sectioned element adhesive film;

sticking the sectioned [[an]] element adhesive film, ~~which is sectioned according to the shape of one of the semiconductor elements,~~ held by the porous absorption member to each of the back surfaces of the picked-up first and second semiconductor elements held by the absorption collet in order of their sectioning;

sending the first and second semiconductor elements stuck to the sectioned element adhesive film above a semiconductor device forming base material in order of their sectioning;

adhering the first semiconductor element to the semiconductor device forming base material by the element adhesive film; and

adhering the second semiconductor element on the first semiconductor element by the element adhesive film.

2. (Original) The method of manufacturing a semiconductor device according to claim 1,

wherein the semiconductor element sectioning process has a process of sticking the holding member to the back surface of the semiconductor wafer and cutting the semiconductor wafer to form the sectioned semiconductor elements while keeping them in a state being held by the holding member.

3. (Original) The method of manufacturing a semiconductor device according to claim 1,

wherein the semiconductor element sectioning process has a process of forming modified layers or grooves, which are deeper than the thickness of the semiconductor element, from the front surface of the semiconductor wafer, a process of sticking a first holding member to the front surface of the semiconductor wafer, grinding and polishing the back surface of the semiconductor wafer and sectioning the semiconductor elements while keeping them in a state being held by the first holding member, and a process of sticking a second holding member to the back surfaces of the semiconductor elements and separating the first holding member.

4. (Currently Amended) The method of manufacturing a semiconductor device according to claim 1, ~~further comprising:~~

wherein the element adhesive film cutting process has a process of cutting the supplying  
a long element adhesive film supplied from a supply roll ~~and cutting the long element adhesive~~  
~~film according to the shape of the semiconductor element~~ by mechanical cutting or laser cutting  
~~to form the sectioned element adhesive film.~~

5. (Cancelled)

6. (Currently Amended) A manufacturing apparatus of a semiconductor device,  
comprising:

a pickup section for picking up sectioned first and second semiconductor elements by  
holding them with an absorption collet in order of their sectioning from a semiconductor wafer  
which has sectioned semiconductor elements being held by a holding member;

a film cutting section for cutting an element adhesive film held by a porous absorption  
member according to the shape of one of the semiconductor elements to form a sectioned  
element adhesive film;

a film sticking section for sticking ~~[[an]]~~ the sectioned element adhesive film, ~~which is~~  
~~sectioned according to the shape of one of the semiconductor elements,~~ held by the porous  
absorption member to each of the back surfaces of the picked-up first and second semiconductor  
elements held by the absorption collet;

a moving section for moving the first and second semiconductor elements stuck to the  
sectioned element adhesive ~~[[films]]~~ film above a semiconductor device forming base material in  
order of their sectioning; and

an element adhesion section for adhering the first semiconductor element to the semiconductor device forming base material by the element adhesive film and adhering the second semiconductor element on the first semiconductor element by the element adhesive film.

7. (Currently Amended) The manufacturing apparatus of a semiconductor device according to claim 6,

wherein the film ~~sticking section has a film supply section for supplying a long element adhesive film from a supply roll and a film~~ cutting section has a cutting mechanism for cutting the ~~the~~ long element adhesive film supplied from ~~the~~ a supply roll ~~according to the shape of the semiconductor element~~ by mechanical cutting or laser cutting.

8. (Currently Amended) The manufacturing apparatus of a semiconductor device according to claim ~~[[7]]~~ 6,

wherein the film cutting section has ~~an adsorption member for holding the element adhesive film and~~ a cutting mechanism for cutting the element adhesive film ~~[[being]]~~ held by the porous adsorption member by stamping it.

9. (Currently Amended) The manufacturing apparatus of a semiconductor device according to claim 8,

wherein the porous adsorption member is made of a porous metal.

10. (Currently Amended) The manufacturing apparatus of a semiconductor device according to claim ~~[[7]]~~ 6,

wherein the film cutting section has ~~an adsorption member for holding the element~~  
~~adhesive film~~, a laser cutting mechanism for cutting the element adhesive film ~~[[being]]~~ held by  
the porous adsorption member~~[[,]]~~ and a moving mechanism for moving the laser cutting  
mechanism or the porous adsorption member according to the shape of the semiconductor  
element.

11. (Currently Amended) The manufacturing apparatus of a semiconductor device  
according to claim 10,

wherein the porous adsorption member is made of a porous metal.

12. (Currently Amended) The manufacturing apparatus of a semiconductor device  
according to claim 6,

wherein the pickup section has ~~an adsorption collet for holding the semiconductor~~  
~~element~~ and a push-up mechanism for separating the semiconductor element ~~[[being]]~~ held by  
the adsorption collet from the holding member by pushing up the back surface of the  
semiconductor element.

13. (Currently Amended) The manufacturing apparatus of a semiconductor device  
according to claim ~~[[12]]~~ 6,

wherein the adsorption collet is made of a porous metal.

14. (Previously Presented) The manufacturing apparatus of a semiconductor device  
according to claim 6,

wherein the film sticking section has a film separation section for separating a protective film, which is disposed on the back surface of the element adhesive film stuck to the semiconductor element.

15. (Previously Presented) The method of manufacturing a semiconductor device according to claim 1,

wherein the second semiconductor element is stacked on the first semiconductor element such that the second semiconductor element protrudes from the outside shape of the first semiconductor element.

16. (Previously Presented) The manufacturing apparatus of a semiconductor device according to claim 6,

wherein the second semiconductor element is stacked on the first semiconductor element such that the second semiconductor element protrudes from the outside shape of the first semiconductor element.